ABSTRACT OF THE DISCLOSURE

An insulating adhesive for electronic parts, which is to be used for bonding a semiconductor chip to a lead frame and comprises a resin and a solvent, the resin having

(A) a weight average molecular weight (Mw) of 30,000 to 300,000 based on conversion into polystyrene and

(B) a ratio of weight average molecular weight (Mw)/number average molecular weight (Mn) of 5 or less,

and (C) the insulating adhesive for electronic parts having a viscosity of 5,000 to 100,000 mPa·s at a rotation number of 10 rpm and a viscosity ratio (η1rpm/η10rpm) of 1.0 to 6.0 as measured at 25°C with an E-type viscometer.